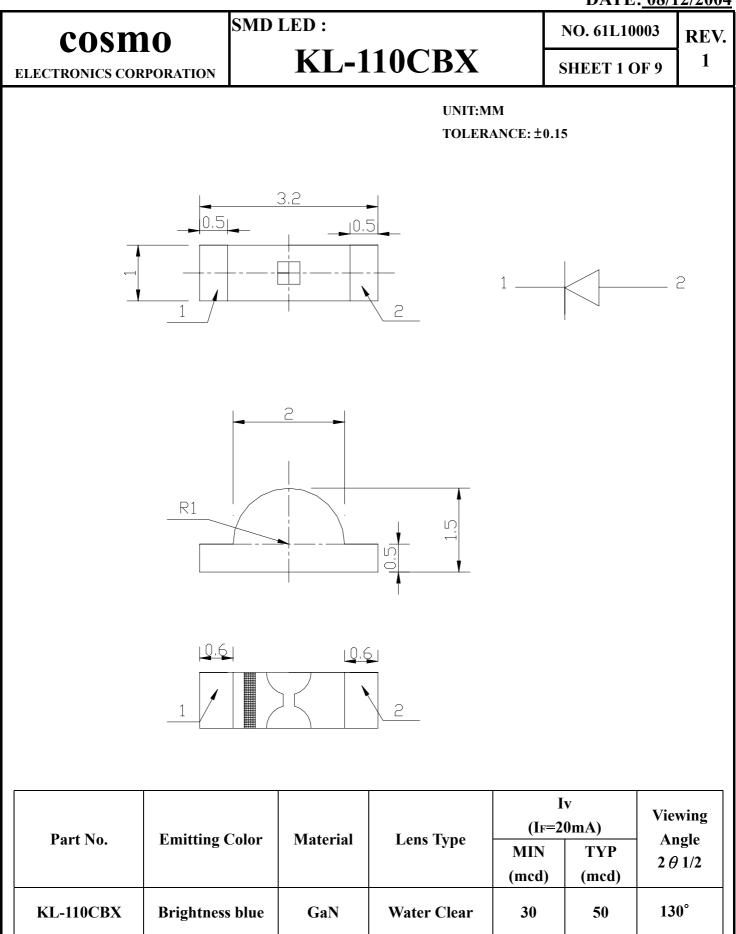
DATE: 08/12/2004



DATE: 08/12/2004

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KL-110CBX

 NO. 61L10003
 REV.

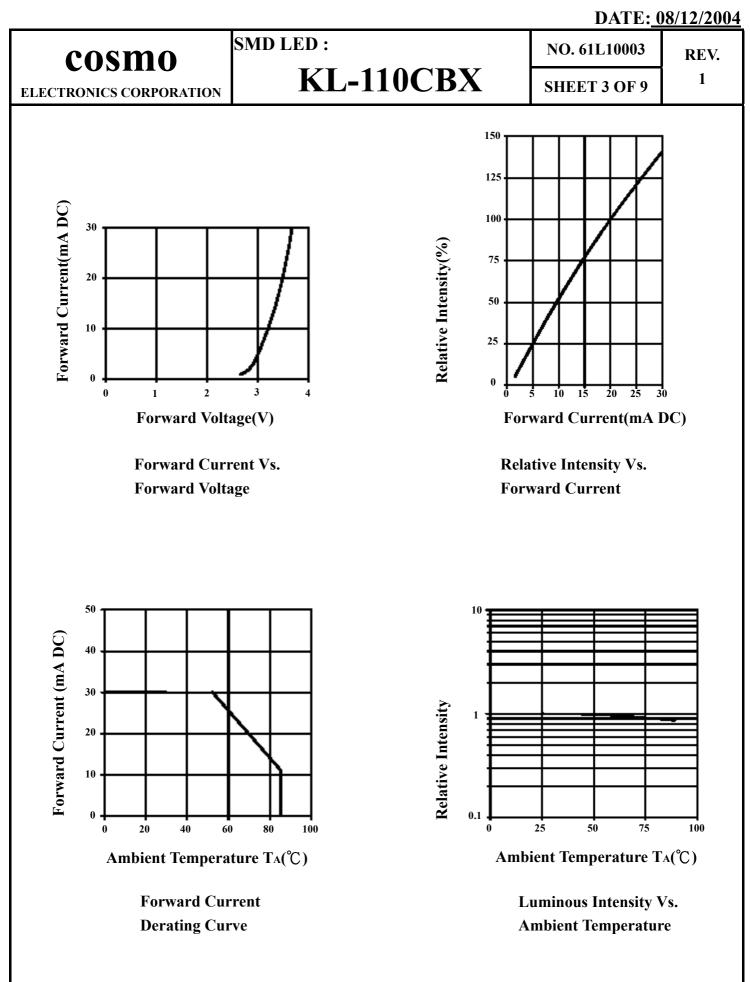
 SHEET 2 OF 9
 1

ELECTRONICS CORPORATION

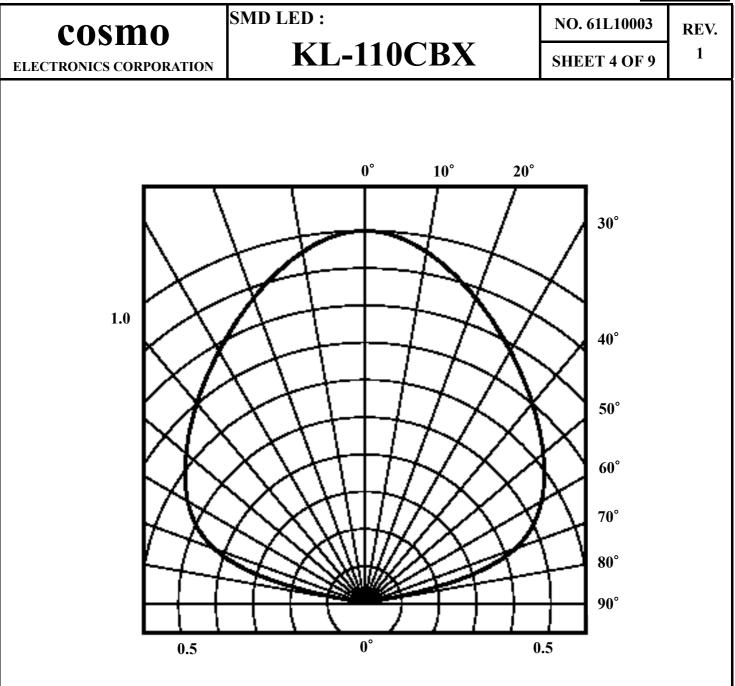
Absolute maximum ratings (TA=25°C)		QB Blue (GaN)	Unit
Reverse voltage	VR	5	V
Forward current	IF	30	mA
Forward current(Peak)	Ifp	100	mA
1/10 Duty Cycle,0.1ms Pulse Width			
Power dissipation	Pd	90	mW
LED LAMPS:			
Operating temperature	Тор	-40~+85	°C
Storage temperature	Тят	-40~+85	°C
LED DISPLAYS:			
Operating temperature	Та	-40~+85	°C
Storage temperature	Tstg	-40~+85	°C

Operating characteristics (TA=25°C)		QB Blue (GaN)	Unit
Forward voltage(typ.) IF=20mA	VF	3.7	V
Forward voltage(max.) IF=20mA	VF	4.0	V
Reverse current(max.) V _R =5V	Ir	10	uA
Wavelength at dominant emission(typ.) IF=20mA	λο	470	nm
Wavelength at peak emission(typ.) IF=20mA	λp	-	nm
Spectral line half-width IF=20mA	Δ λ	65	nm
Capacitance VF=0V,f=1MHz	С	100	pF

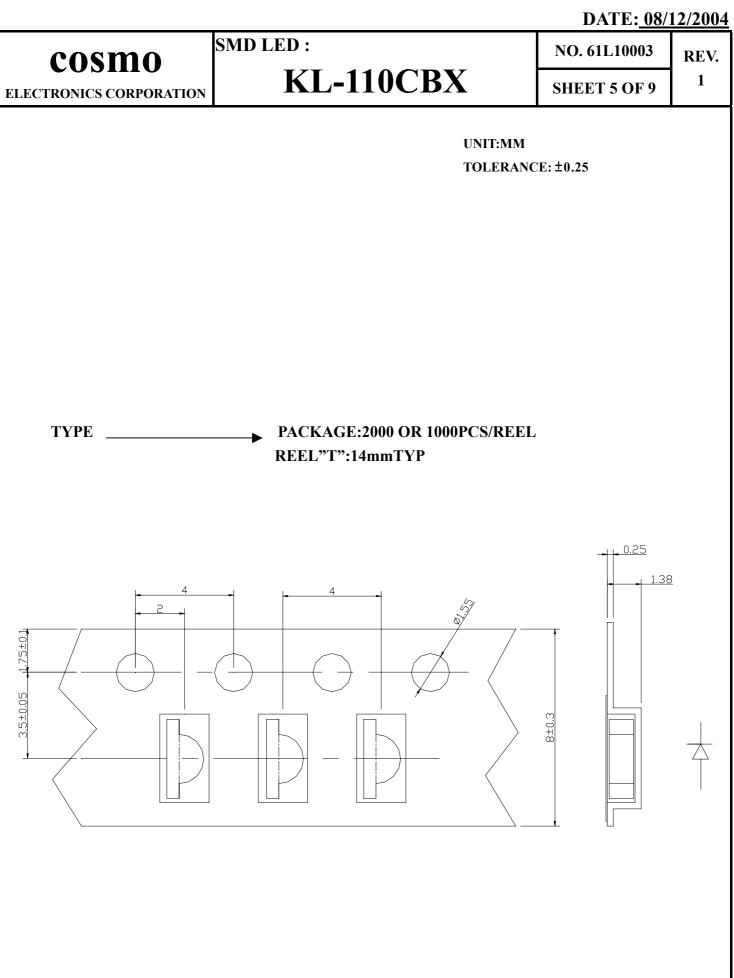
SMD LED :

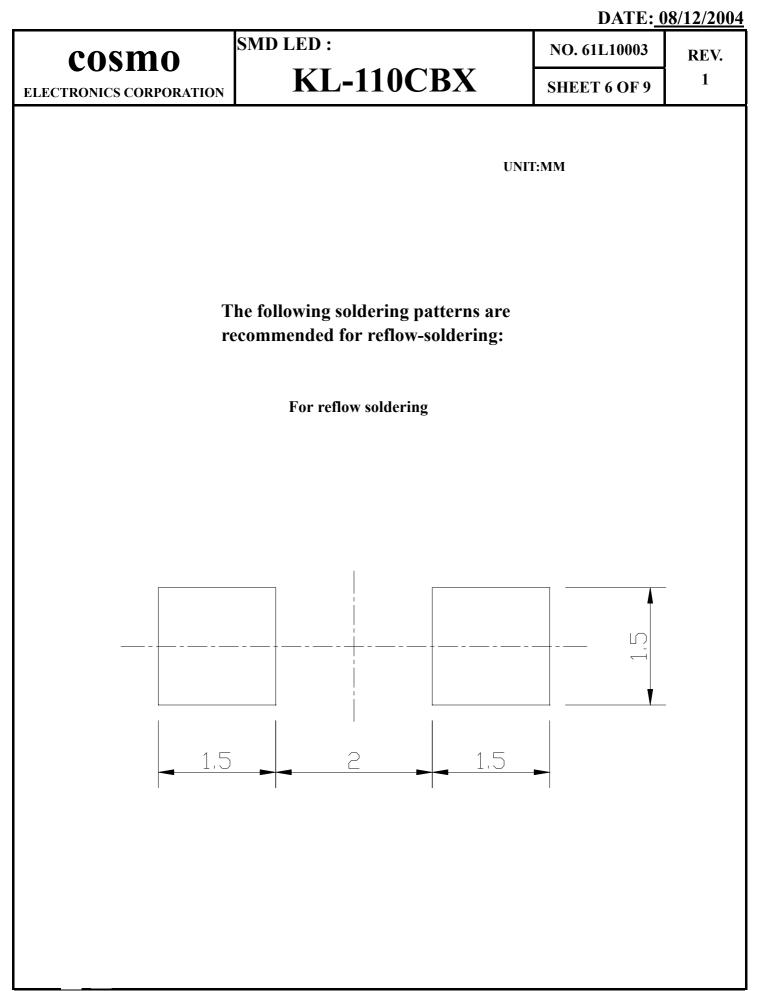


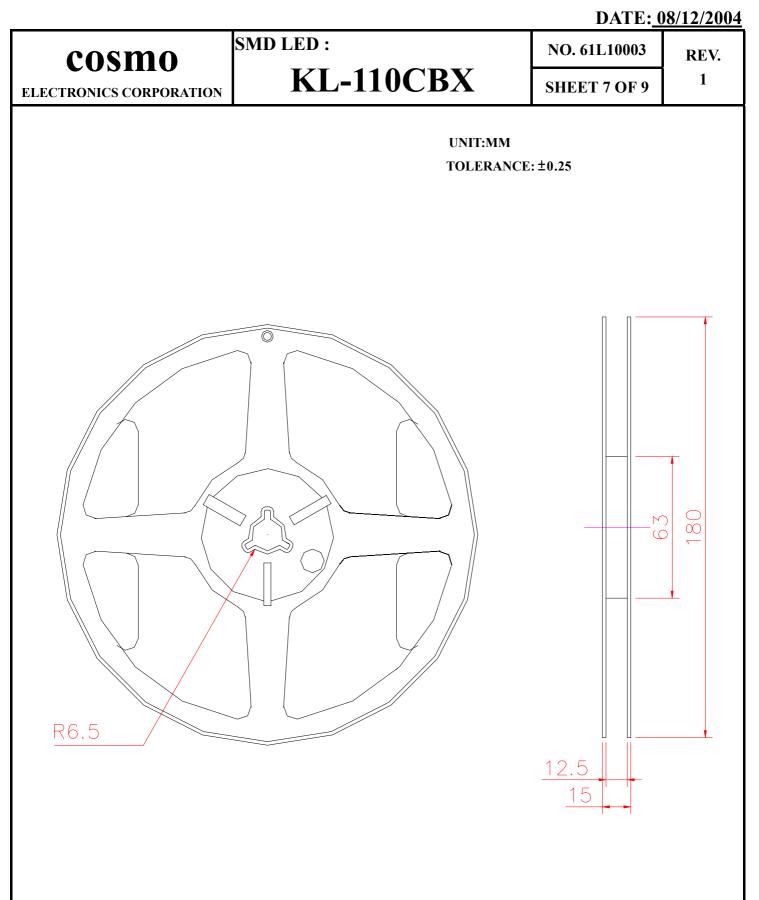
DATE: 08/12/2004



View Angle 2 ∂1/2=130°







DATE: 08/12/2004 **SMD LED :** NO. 61L10003 cosmo REV. **KL-110CBX** 1 **SHEET 8 OF 9 ELECTRONICS CORPORATION SOLDERING** SMT REFLOW SOLDERING **INSTRUCTIONS** 10 sec MAX Temp (°C) TEMPERATURE 230 4° C/sec max 140~160°C 4° C/sec max Time 35sec MAX -60~120sec-SOLDERING INSRTUCTIONS **DIP AND WAVE SOLDERING** IRON SOLDERING(WITH 1.5mm IRON TIP) **TYPES TEMPERATURE OF** DISTANCE FROM MAXLMUM **DISTANCE FORM TEMPERATURE OF** MAXLMUM THE SOLDERING SOLDERING SOLDER JOINT SOLDERING SOLDERING SOLDER JOINT BATH TIME **TO CASE** IRON TIME **TO CASE** >2mm ≦**260**°C 3S >2mm **≦260**°C 3S LEDS ≦**260**°C 5S >4mm ≦**260**°C **5**S >4mm DISPLAYS ≤**260**°C >2mm >2mm 3S ≤**260**°C 3S

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SMD LED :

KL-110CBX

SMD HANDLING AND APPLICATION PRECAUTIONS

STORAGE

(1.1) It is recommended to store the devices in accordance with the following conditions:

Humidity: 60%RH Max.

Temperature: $5^{\circ}C \sim 30^{\circ}C$ (41°F ~ 86°F)

(1.2)Shelf life in sealed bag: 12 month at $<5^{\circ}$ C $\sim30^{\circ}$ C and $<30^{\circ}$ RH. After the package is opened, the products should be used within 72hrs. Or they should be kept at $\leq 20\%$ RH in zip -locked sealed bags.

DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hrs, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- (a) $60\pm3^{\circ}$ C x (12~24hrs) and <5%RH, taped reel type
- (b) $100\pm3^{\circ}C$ x (45min~1hr), loose packing type, or
- (c) $130\pm3^{\circ}C$ x (15~30min), loose packing type

ELECTRIC STATIC DISCHARGE(ESD) PROTECTION

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberatively observed from the initial design stage. The static -electric discharge may result in severe malfunction of the devices. In the events of manual working in process, make sure the devices are well protected from ESD at any time. Surge before and during handling products.

NO. 61L10003 REV. SHEET 9 OF 9

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